

GRINDING PARAMETERS

FOR RESIN BOND DIAMOND & CBN WHEELS

Grinding Process	Parameter		For Diamond	For CBN
Surface Grinding	Cutting Speed (m/s)		23 - 26	28 - 23
	Oscillation (m/min)		8 - 15	10 - 20
	Depth of cut (mm)	Roughing Finishing	0.05 - 0.08 0.002 - 0.02	0.06 - 0.1 0.005 - 0.03
External Cylindrical Grinding	Cutting Speed (m/s)		23 - 26	28 - 23
	Oscillation (m/min)		5 - 15	10 - 20
	Workpiece Speed (m/min)		10 - 20	10 - 20
	Depth of cut/infeed (mm)	Roughing Finishing	0.03 - 0.05 0.003 - 0.02	0.04 - 0.08 0.004 - 0.03
Internal Grinding	Cutting Speed (m/s)	Resin Bond Electroplated	15 - 20 5 - 10	18 - 25 8 - 15
	Oscillation (m/min)		2 - 3	3 - 5
	Workpiece Speed (m/min)		25 - 30	30 - 35
	Depth of cut/infeed (mm)	Roughing Finishing	0.003 - 0.02 0.003 - 0.008	0.003 - 0.03 0.003 - 0.05
Tool & Cutter Grinding	Cutting Speed (m/s)	Wet Dry	18 - 25 15 - 18	25 - 35 18 - 30
	Table Speed (m/min)		2 - 3	3 - 5
	Workpiece Speed (m/min)		25 - 30	30 - 35
	Depth of cut/infeed (mm)		0.02 - 0.2	0.02 - 0.3
Creep-feed Grinding	Cutting Speed (m/s)		25 - 30	30 - 45
	Feed Rate (mm/min)		25 - 250	50 - 750
	Depth of cut		Total Allowance	Total Allowance